

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW RESONATOR  
MODEL NO 型号: \_\_\_\_\_ HDR868.985MS205  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2016-7-16

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited



## 1. SCOPE

This specification shall cover the characteristics of 1-port SAW resonator with 868.35M used for remote-control security.

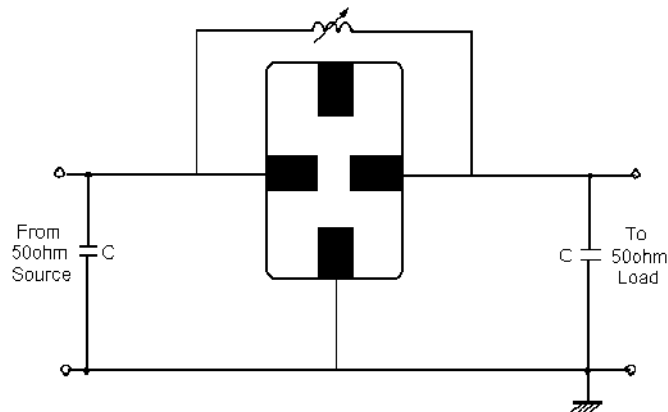
## 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

### 2.2 Electronic Characteristics

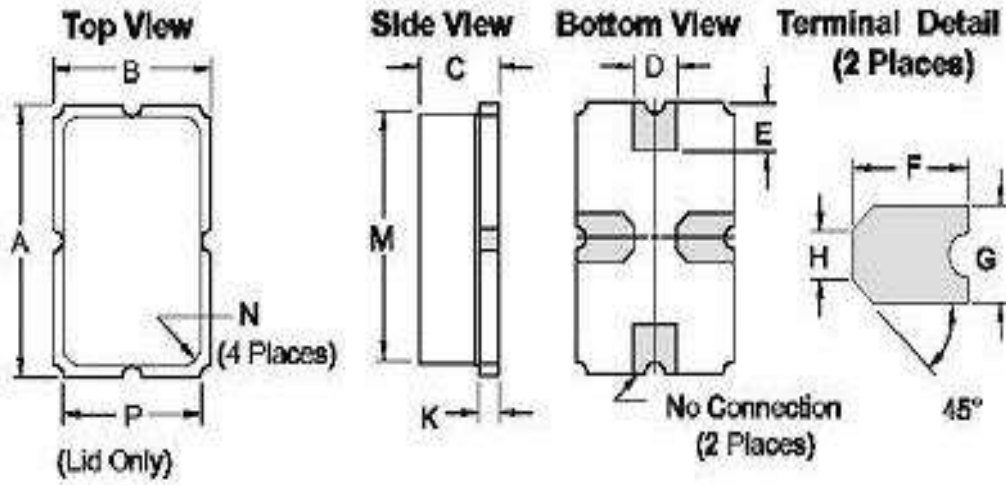
Item	Unites	Minimum	Typical	Maximum	
Center Frequency	MHz	868.735	868.985	869.235	
Insertion Loss	dB		1.5	2.5	
Quality Factor Unload Q		10000	12800		
50Ω Loaded Q		1000	2000		
Temperature Stability	Turnover Temperature	°C	10	25	40
	Freq.temp.Coefficient	ppm/°C <sup>2</sup>		0.037	
Frequency Aging	ppm/yr		<±10		
DC. Insulation Resistance	MΩ	1.0			
RF Equivalent RLC Model	Motional Resistance R1	Ω	23	26	
	Motional Inductance L1	μ H	20.773		
	Motional Capacitance C1	fF	1.6173		
Transducer Static Capacitance	pF		1.8		

## 3. TEST CIRCUIT



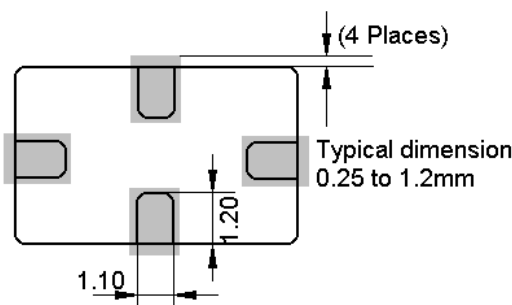
**4. DIMENSION**

4-1 Typical dimension(unit:mm)



Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A		5.97		0.235
B		3.94		0.155
C		2.16		0.085
D	0.94	1.10	0.037	0.043
E	0.83	1.20	0.033	0.047
F	1.16	1.53	0.046	0.060
G	0.94	1.10	0.037	0.043
H	0.43	0.59	0.017	0.023
K	0.43	0.59	0.17	0.023
M		5.31		0.209
N	0.38	0.64	0.015	0.025
P		3.28		0.129

4-2 Typical circuit board land patter



## **5. ENVIRONMENTAL CHARACTERISTICS**

### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2.2.

### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2.

### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the resonator shall fulfill the specifications in 2.2.

### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The resonator shall fulfill the specifications in 2.2.

## **6. REMARK**

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.